

**60V DUAL N-CHANNEL ENHANCEMENT MODE MOSFET**
**Product Summary**

| $V_{(BR)DSS}$ | $R_{DS(on)}$                   | $I_D$<br>$T_A = +25^\circ C$ |
|---------------|--------------------------------|------------------------------|
| 60V           | 66m $\Omega$ @ $V_{GS} = 10V$  | 4.4A                         |
|               | 97m $\Omega$ @ $V_{GS} = 4.5V$ | 3.6A                         |

**Features and Benefits**

- Low on-resistance
- Fast switching speed
- 100% Unclamped Inductive Switch (UIS) test in production
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP Capable (Note 4)**

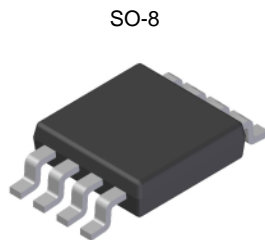
**Description and Applications**

This MOSFET is designed to minimize the on-state resistance and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

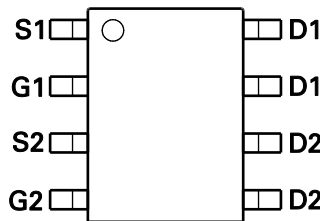
- Motor Control
- Backlighting
- DC-DC Converters
- Power Management Functions

**Mechanical Data**

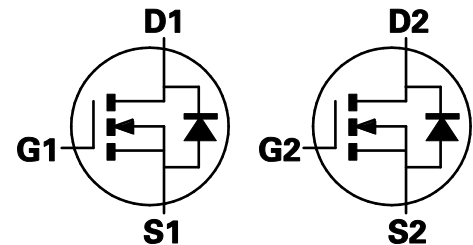
- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See Diagram Below
- Terminals: Finish - Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (E3)
- Weight: 0.074 grams (Approximate)



Top View



Top View



Equivalent Circuit

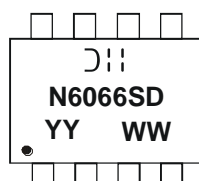
**Ordering Information** (Notes 4 & 5)

| Part Number    | Compliance | Case | Packaging         |
|----------------|------------|------|-------------------|
| DMN6066SSD-13  | Commercial | SO-8 | 2,500/Tape & Reel |
| DMN6066SSDQ-13 | Automotive | SO-8 | 2,500/Tape & Reel |

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to [http://www.diodes.com/quality/product\\_grade\\_definitions/](http://www.diodes.com/quality/product_grade_definitions/).
  5. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

**Marking Information**

SO-8



= Manufacturer's Marking  
 N6066SD = Product Type Marking Code  
 YYWW = Date Code Marking  
 YY = Year (ex: 09 = 2009)  
 WW = Week (01 - 53)

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

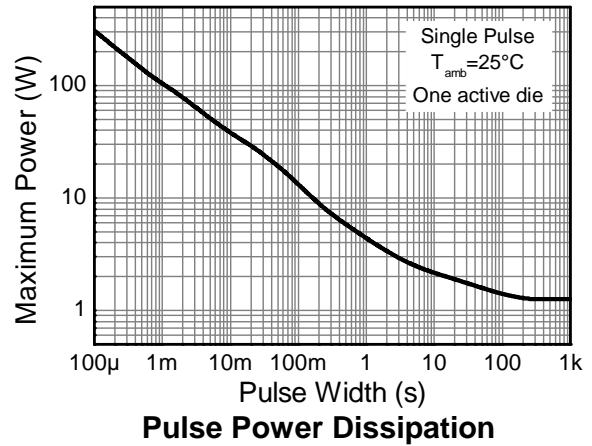
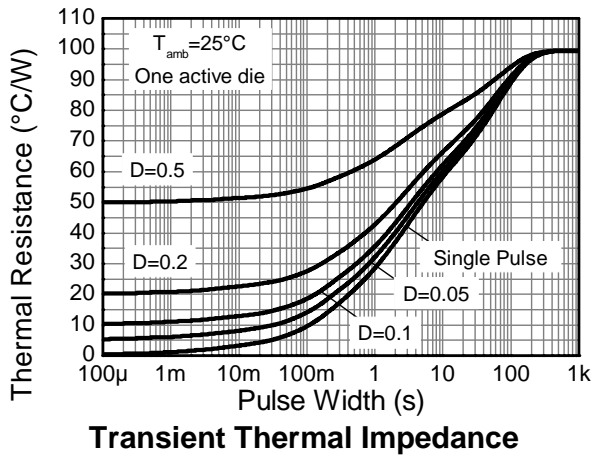
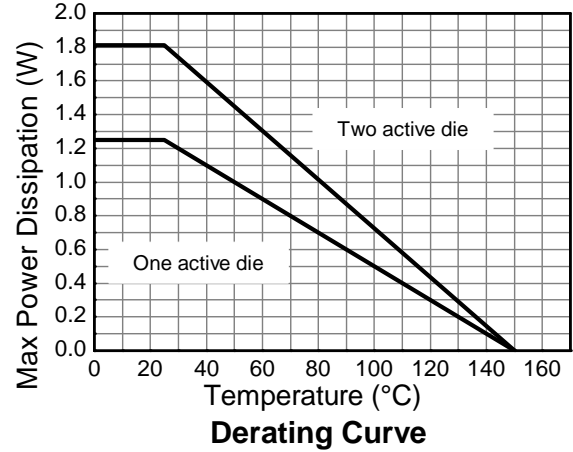
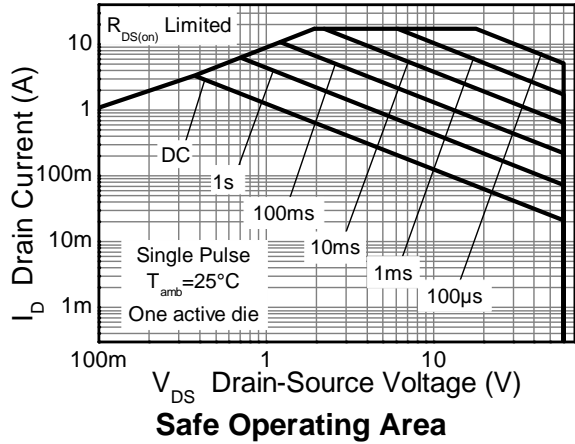
| Characteristic                         |                                | Symbol                          | Value | Unit |
|--|--------------------------------|---------------------------------|-------|------|
| Drain-Source Voltage                   |                                | V <sub>DSS</sub>                | 60    | V    |
| Gate-Source Voltage                    | (Note 6)                       | V <sub>GS</sub>                 | ±20   | V    |
| Single Pulsed Avalanche Energy         | (Note 13)                      | E <sub>AS</sub>                 | 37.5  | mJ   |
| Single Pulsed Avalanche Current        | (Note 13)                      | I <sub>AS</sub>                 | 5.0   | A    |
| Continuous Drain Current               | V <sub>GS</sub> = 10V          | (Note 8)                        | 4.4   | A    |
|  |                                | T <sub>A</sub> = +70°C (Note 8) | 3.5   |      |
|  |                                | (Note 7)                        | 3.3   |      |
| Pulsed Drain Current                   | V <sub>GS</sub> = 10V (Note 9) | I <sub>DM</sub>                 | 17.0  | A    |
| Continuous Source Current (Body diode) | (Note 8)                       | I <sub>S</sub>                  | 3.2   | A    |
| Pulsed Source Current (Body diode)     | (Note 9)                       | I <sub>SM</sub>                 | 17.0  | A    |

**Thermal Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

| Characteristic                              |                 | Symbol                            | Value      | Unit       |
|---|-----------------|-----------------------------------|------------|------------|
| Power Dissipation<br>Linear Derating Factor | (Notes 7 & 10)  | P <sub>D</sub>                    | 1.25       | W<br>mW/°C |
|   |                 |                                   | 10         |            |
|   | (Notes 7 & 11)  |                                   | 1.8        |            |
|   |                 |                                   | 14.3       |            |
| Thermal Resistance, Junction to Ambient     | (Notes 8 & 10)  | R <sub>θJA</sub>                  | 2.14       | °C/W       |
|   |                 |                                   | 17.2       |            |
|   | (Notes 7 & 10)  |                                   | 100        |            |
| Thermal Resistance, Junction to Ambient     | (Notes 7 & 11)  | R <sub>θJA</sub>                  | 70         | °C/W       |
|   | (Notes 8 & 10)  |                                   | 58         |            |
| Thermal Resistance, Junction to Lead        | (Notes 10 & 12) | R <sub>θJL</sub>                  | 55         | °C/W       |
| Operating and Storage Temperature Range     |                 | T <sub>J</sub> , T <sub>STG</sub> | -55 to 150 | °C         |

- Notes:
- AEC-Q101 V<sub>GS</sub> maximum is ±16V.
  - For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
  - Same as note (3), except the device is measured at t ≤ 10 sec.
  - Same as note (3), except the device is pulsed with D = 0.02 and pulse width 300µs. The pulse current is limited by the maximum junction temperature.
  - For a dual device with one active die.
  - For a device with two active die running at equal power.
  - Thermal resistance from junction to solder-point (at the end of the drain lead).
  - UIS in production with L = 3.0mH, I<sub>AS</sub> = 5.0A, R<sub>G</sub> = 25Ω, V<sub>DD</sub> = 50V, starting T<sub>J</sub> = +25°C.

**Thermal Characteristics**

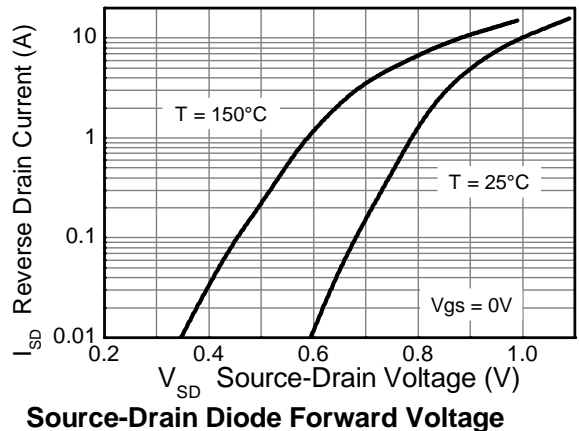
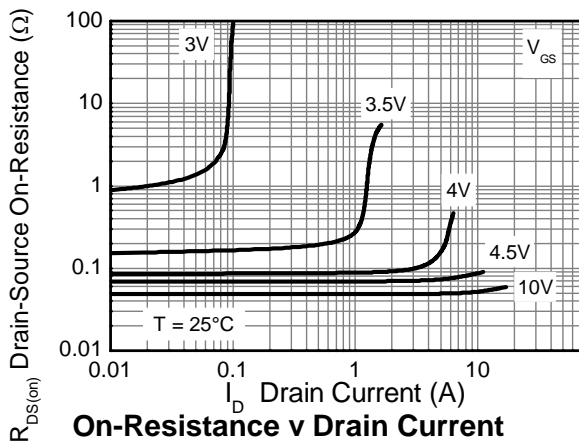
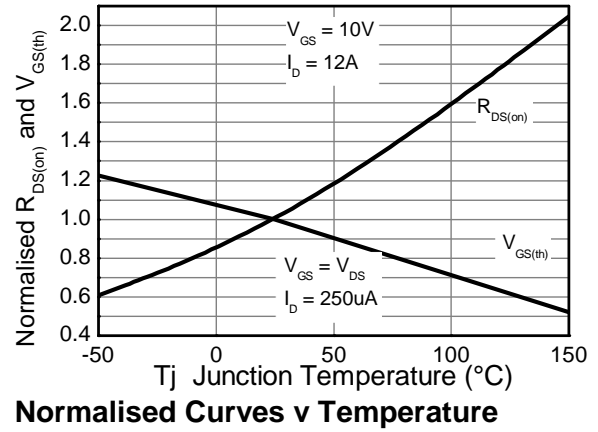
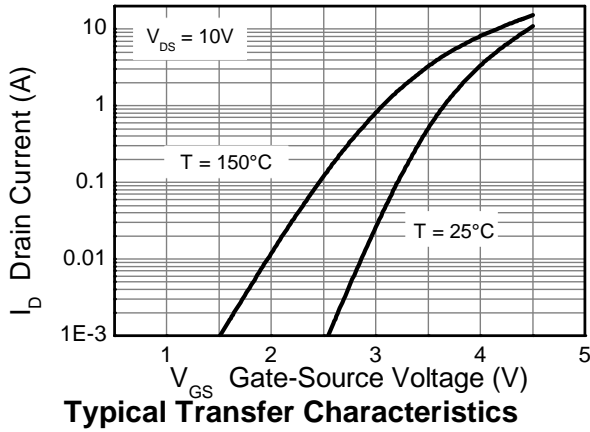
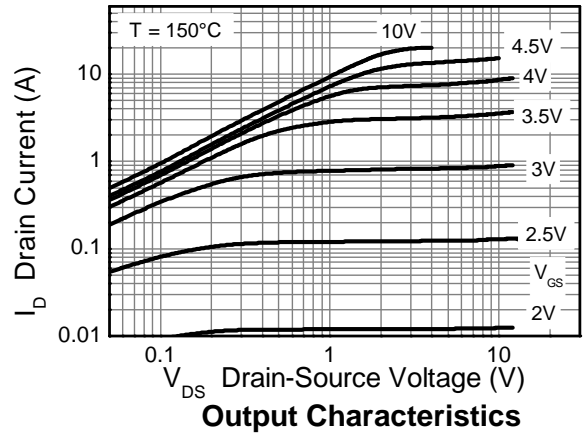
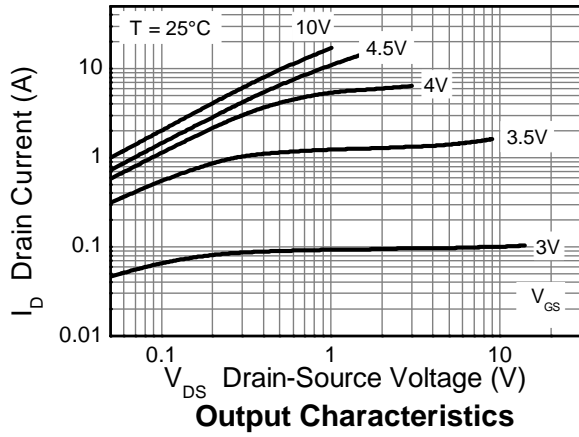


**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

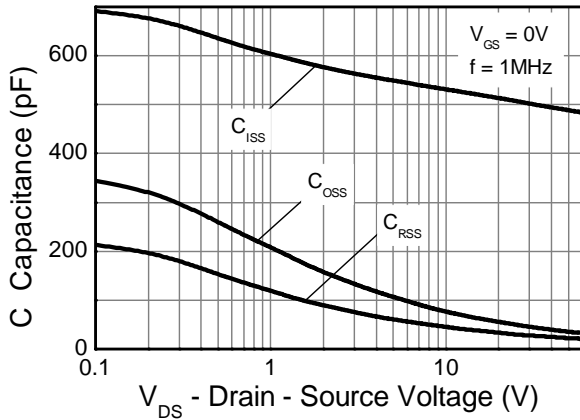
| Characteristic                              | Symbol              | Min | Typ   | Max   | Unit | Test Condition   |
|---|---------------------|-----|-------|-------|------|--|
| <b>OFF CHARACTERISTICS</b>                  |                     |     |       |       |      |  |
| Drain-Source Breakdown Voltage              | BV <sub>DSS</sub>   | 60  | —     | —     | V    | I <sub>D</sub> = 250μA, V <sub>GS</sub> = 0V   |
| Zero Gate Voltage Drain Current             | I <sub>DSS</sub>    | —   | —     | 0.5   | μA   | V <sub>DS</sub> = 60V, V <sub>GS</sub> = 0V  |
| Gate-Source Leakage                         | I <sub>GSS</sub>    | —   | —     | ±100  | nA   | V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V   |
| <b>ON CHARACTERISTICS</b>                   |                     |     |       |       |      |  |
| Gate Threshold Voltage                      | V <sub>GS(th)</sub> | 1.0 | —     | 3.0   | V    | I <sub>D</sub> = 250μA, V <sub>DS</sub> = V <sub>GS</sub>                                  |
| Static Drain-Source On-Resistance (Note 14) | R <sub>DS(on)</sub> | —   | 0.048 | 0.066 | Ω    | V <sub>GS</sub> = 10V, I <sub>D</sub> = 4.5A   |
|   |                     |     | 0.068 | 0.097 |      | V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 3.5A  |
| Forward Transconductance (Notes 14 & 15)    | g <sub>fs</sub>     | —   | 19.2  | —     | S    | V <sub>DS</sub> = 15V, I <sub>D</sub> = 6A   |
| Diode Forward Voltage (Note 14)             | V <sub>SD</sub>     | —   | 0.89  | 1.15  | V    | I <sub>S</sub> = 4.5A, V <sub>GS</sub> = 0V  |
| Reverse recovery time (Note 15)             | t <sub>rr</sub>     | —   | 22.2  | —     | ns   | I <sub>S</sub> = 1.9A, di/dt = 100A/μs   |
| Reverse recovery charge (Note 15)           | Q <sub>rr</sub>     | —   | 16.9  | —     | nC   |  |
| <b>DYNAMIC CHARACTERISTICS (Note 15)</b>    |                     |     |       |       |      |  |
| Input Capacitance                           | C <sub>iss</sub>    | —   | 502   | —     | pF   | V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V<br>f = 1MHz                                    |
| Output Capacitance                          | C <sub>oss</sub>    | —   | 45.7  | —     | pF   |  |
| Reverse Transfer Capacitance                | C <sub>rss</sub>    | —   | 27.1  | —     | pF   |  |
| Total Gate Charge (Note 16)                 | Q <sub>g</sub>      | —   | 5.4   | —     | nC   | V <sub>GS</sub> = 4.5V   |
| Total Gate Charge (Note 16)                 | Q <sub>g</sub>      | —   | 10.3  | —     | nC   | V <sub>GS</sub> = 10V  |
| Gate-Source Charge (Note 16)                | Q <sub>gs</sub>     | —   | 1.7   | —     | nC   |  |
| Gate-Drain Charge (Note 16)                 | Q <sub>gd</sub>     | —   | 3.2   | —     | nC   |  |
| Turn-On Delay Time (Note 16)                | t <sub>D(on)</sub>  | —   | 2.7   | —     | ns   | V <sub>DD</sub> = 30V, V <sub>GS</sub> = 10V<br>I <sub>D</sub> = 1A, R <sub>G</sub> = 6.0Ω |
| Turn-On Rise Time (Note 16)                 | t <sub>r</sub>      | —   | 2.4   | —     | ns   |  |
| Turn-Off Delay Time (Note 16)               | t <sub>D(off)</sub> | —   | 14.7  | —     | ns   |  |
| Turn-Off Fall Time (Note 16)                | t <sub>f</sub>      | —   | 5.4   | —     | ns   |  |

- Notes:
14. Measured under pulsed conditions. Pulse width ≤ 300μs; duty cycle ≤ 2%.
  15. For design aid only, not subject to production testing.
  16. Switching characteristics are independent of operating junction temperatures.

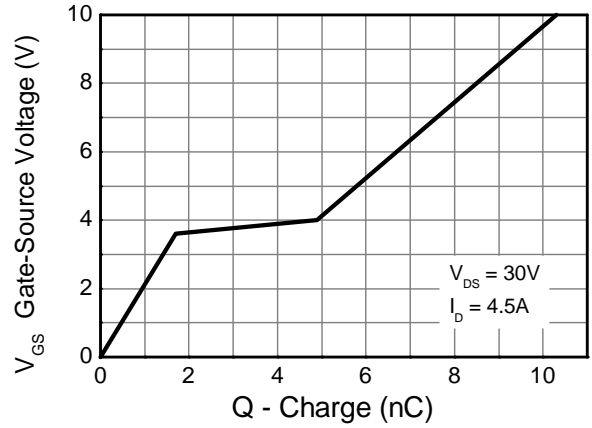
**Typical Characteristics**



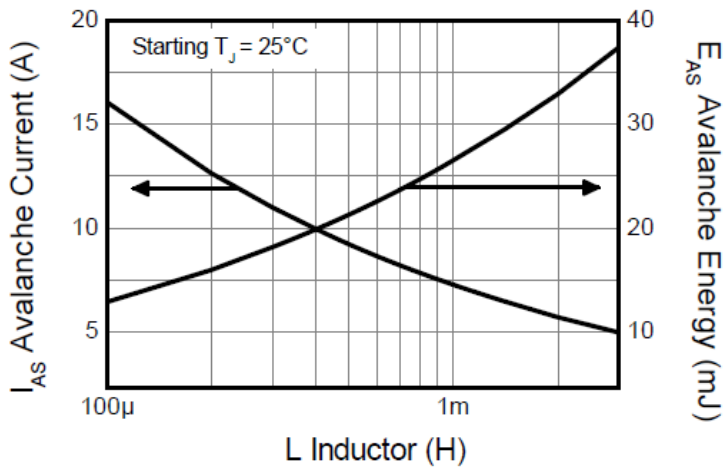
**Typical Characteristics** (continued)



**Capacitance v Drain-Source Voltage**

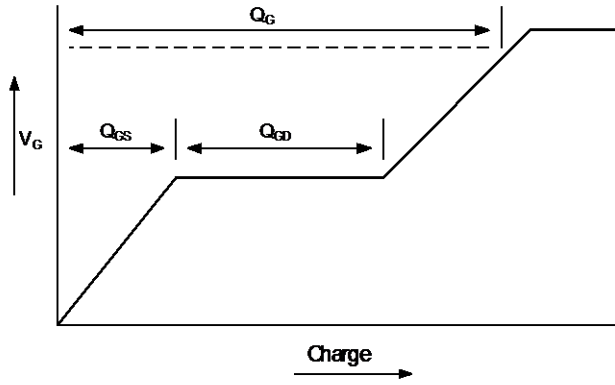


**Gate-Source Voltage v Gate Charge**

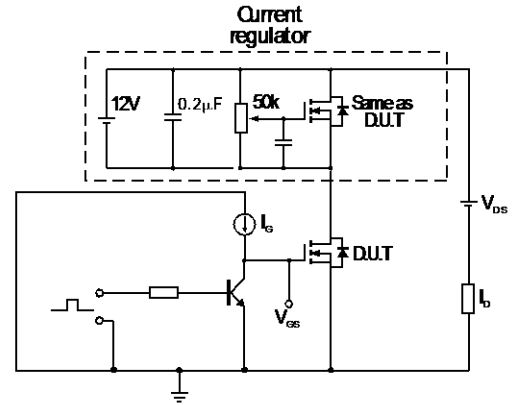


**Single-Pulsed Avalanche Rating**

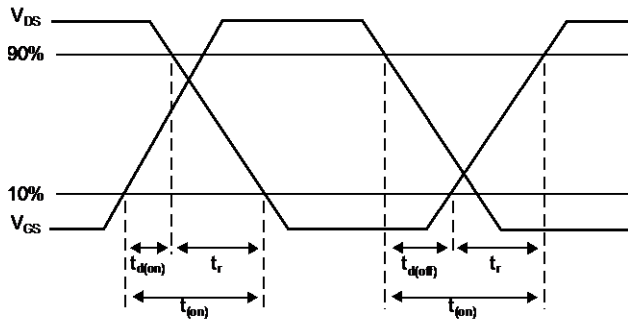
**Test Circuits**



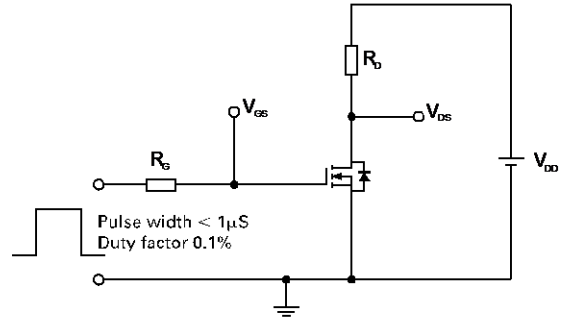
**Basic gate charge waveform**



**Gate charge test circuit**



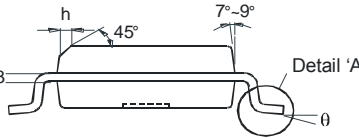
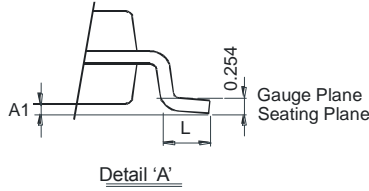
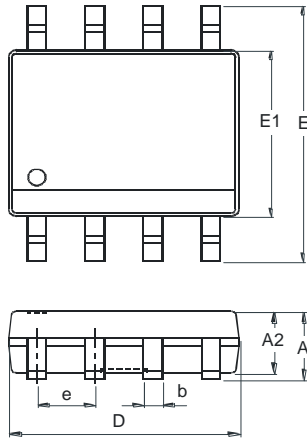
**Switching time waveforms**



**Switching time test circuit**

**Package Outline Dimensions**

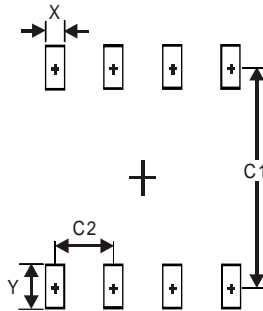
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



| SO-8                        |          |      |
|-----------------------------|----------|------|
| Dim                         | Min      | Max  |
| A                           | -        | 1.75 |
| A1                          | 0.10     | 0.20 |
| A2                          | 1.30     | 1.50 |
| A3                          | 0.15     | 0.25 |
| b                           | 0.3      | 0.5  |
| D                           | 4.85     | 4.95 |
| E                           | 5.90     | 6.10 |
| E1                          | 3.85     | 3.95 |
| e                           | 1.27 Typ |      |
| h                           | -        | 0.35 |
| L                           | 0.62     | 0.82 |
| θ                           | 0°       | 8°   |
| <b>All Dimensions in mm</b> |          |      |

**Suggested Pad Layout**

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



| Dimensions | Value (in mm) |
|------------|---------------|
| X          | 0.60          |
| Y          | 1.55          |
| C1         | 5.4           |
| C2         | 1.27          |



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